IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under bo international and Pan-American copyright conventions.			nder both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1					Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					eous Materia	als and Mfg	Informati	ion	
Supplier	Information														
Company name*				ompany unique ID			Unique ID Authority					Response Date*			
nsemi												2025-07-06			
Contact Na	ame	Title - Contact			F	Phone - Contact*					Email - Contact*				
Product-E	Env-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com					
uthorized	l Representative*	Title - Representative			F	Phone - Representative*				Email - Representative*					
Product-E	Env-Stewards	Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mf		Item Number Mfr Item Name				Effective Date	Versio	on N	Manufacturing Site		W	eight*	UOM	Unit Type
		NCV6323DMTAAWT DCDC BUCK CO BG WETTABLE FLA			SLP	2025-07-06	MY1			9.0)4	mg	Each		
Ianufac	cturing Proccess Informa	ation													
	Terminal Plating / Grid Array M	Terminal Base Alloy J-STD-020 MSI		-STD-020 MSL F	Rating	Peak Process Body Temperature Max Time at Po			ime at Peak	ak Temperature Number of Reflow Cycles					
	Matte Tin (Sn) - annealed		CU Alloy 1			260	0 C 30			seconds	3				
omments	·			·	•									•	
vel 1 - ma	aximum time at peak temperat	ure during so	ldering is 10-3	0 seconds											
or more i	nformation regarding material	l composition	please refer to	page 3	·									·	

RoHS Material Composition Declaration			Declaration Type *	Detail	led						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recruired by the						
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.55	mg	Supplier	Silicon (Si)	7440-21-3		0.55	mg
Die Attach Tape	0.09	mg		Epoxy resin	proprietary data		0.0176	mg
			Supplier	Silver (Ag)	7440-22-4		0.0725	mg
Lead Frame	2.16		Supplier	Silver (Ag)	7440-22-4		0.0432	mg
			Supplier	Tin (Sn)	7440-31-5		0.0054	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0048	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0054	mg
			Supplier	Copper (Cu)	7440-50-8		2.1012	mg
Mold Compound-Black	5.77			Epoxy resin	proprietary data		0.2885	mg
			Supplier	Phenolic Resin	Proprietary Data		0.1327	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.2885	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0231	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.1327	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.9045	mg
Plating	0.39	mg	Supplier	Tin (Sn)	7440-31-5		0.39	mg
Wire Bond - Au	0.08	mg	Supplier	Gold (Au)	7440-57-5		0.08	mg